



The semiconductor rendez-vous

Prague | October 8-10, 2024

Tuesday, October 8 Afternoon

- 13:00 Registration
- 14:00 Welcome speech
- Czech Ministry of Industry & Trade, CNSC, Minalogic
- 14:30 IPCEI ME/CT: what it is about, participants & topics
- VDI/VDE-IT, Facilitation Group
- 15:00 Companies' presentations
- Lynred, Soitec, STMicroelectronics
- 15:10 Microelectronics value chain & ecosystem
- Lynred, Soitec, STMicroelectronics
- 15:55 *Break*
- 16:40 Companies' presentations
- Renault, Valeo, Vitesco Technologies
- 16:50 Power Electronics for beginners
- Renault
- 17:10 Power electronics: requirements and technological challenges for low-cost, low-impact cars
- Valeo, Vitesco Technologies
- 17:50 Individual IPCEI project's presentations
- Renault, Valeo, Vitesco Technologies
- 18:05 End of session

Wednesday, October 9 Morning

- 08:30 Welcoming participants
- 09:00 Companies' presentations
- GlobalWafers, X-FAB
- 09:05 A Foundry Perspective for Automotive Applications & Solutions
- X-FAB
- 09:35 **Panel discussion:** The contribution of innovation to the automotive market
- Lynred, Renault, X-FAB
- 10:05 *Break*
- 10:50 Companies' presentations
- CEA, Murata
- 10:55 Technology and manufacturing solutions for high performance SiC substrates and devices
- Soitec, STMicroelectronics
- 11:25 Affordable thermal imaging for AEB - saving lives in all visibility conditions
- Lynred
- 11:55 Companies' presentations
- Aledia
- 12:00 IPCEI overall result & Application to dashboard backlighting
- Aledia
- 12:30 Presentation of 4 Czech companies in relation with IPCEI ME/CT
- Cudasip, Mycroft Mind, NXP, UJP PRAHA
- 13:00 *Lunch*

Wednesday, October 9 Afternoon

14:15 Welcoming participants

In the Congress Hall

14:30 Heterogeneous and 3D integration

- STMicroelectronics France

15:00 Integrated Silicon Capacitor: Optimization of the performances of advanced processors by using a combination of advanced packaging technologies and ultrathin silicon capacitors

- Murata

15:30 *Break*

16:00 Driving the Future: The Intersection of AI, Automotive Innovation, and Power-Efficient SOI Technologies

- Soitec

16:30 Platform for Power electronics

- Vitesco Technologies

17:00 Technical results from a collaboration induced by IPCEI program

- GlobalWafers

17:30 End of session

19:00 **Gala dinner | Vikarka Restaurant:** You are cordially invited for dinner
Please arrive at 19:00 sharp!

In the Classroom

14:30 Semiconductor IC provider collaboration with telecom apparatus manufacturer towards 5G and beyond cellular network infrastructures

- SIAE Microelettronica

15:00 Innovative substrates for RF: current and future standards technologies of choice

- Soitec

15:30 *Break*

16:00 Advanced Technology for automotive packaging

- STMicroelectronics Malta

16:30 18 nm FDSOI with ePCM

- STMicroelectronics France

Thursday, October 10 Morning

- 08:30 Welcoming participants
- 09:00 European collaborative projects framework
- CEA
- 09:30 **Panel discussion:** Incentive effect of the IPCEI ME/CT on the reduction of environmental impacts
- CEA, Murata, Soitec, Vitesco Technologies
- 10:00 *Break*
- 10:45 **Panel discussion:** Training in microelectronics, job opportunities, matching companies' recruitment needs
- CNSC, Czech Technical University in Prague, GlobalWafers, STMicroelectronics Italy
- 11:15 **Panel discussion:** IPCEI ME/CT Spillovers, a great opportunity for the benefits of EU enterprises, academics & students
- CEA, Facilitation Group, STMicroelectronics France, Valeo
- 11:45 Long term perspectives and future opportunities in semiconductors
- DG Connect / European Commission
- 12:15 Address by the French Embassy in Czechia
- 12:20 Conclusion
- CNSC, Minalogic
- 12:30 Visit to IPCEI partners' stands
- 13:00 *Lunch*
- 14:30 End of the event



IPCEI Microelectronics and
Communication Technologies